| ACCOCIATION CONNECTING | Aterial Composit Copyright 2005. IPC, I International and Pan-Am | Bannockb | urn, Illinois. A | ll rights reserved untions. | under both | This docume level parts, ti | ent is a dec he declara | claration tion end | n of the sub compasses | bstances all lower | within the level ma | e manufactur terials for wl | er listed it hich the m | tem. No nanufac | ote: if the cturer has | item is an asso engineering re | embly with lowe esponsibility. |
|--|---|-------------------|--|-----------------------------|-------------------------|--------------------------------|--|----------------------------|---------------------------|-------------------------|---------------------------------|--------------------------------|----------------------------|--------------------|---------------------------|-----------------------------------|-----------------------------------|
| | IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute | | | | Form Type Distribute | * | Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi | | | | | als and Mfg Information | | | | | |
| Supplier Information | on | | | | | | | | | | | | | | | | |
| Company name* | | | Company unique ID | | | Unique ID Authority | | | | | Response Date* | | | | | | |
| onsemi | | | | | | | | | | | | 2024-05-17 | | | | | |
| Contact Name | | | Title - Contact | | | Phone - Contact* | | | | | Email - Contact* | | | | | | |
| Product-Env-Stewards | | | Product Enviro Compliance | | | NA | | | | | Product-Env-Stewards@onsemi.com | | | | | | |
| Authorized Representative* | | | Title - Representative | | | Phone - Representative* | | | | Email - Representative* | | | | | | | |
| Product-Env-Stewards | | | Product Enviro Compliance | | | NA | | | | | Product-Env-Stewards@onsemi.com | | | | | | |
| Requester Ite | Requester Item Number Mfr Iter | | Number Mfr Item Name | | | | Effective | Date | Version | Ν | Manufacturing Site | | 1 | Weight | t* | UOM | Unit Type |
| | | | 300 mA Low Iq, Wide Input Voltage LDO - TSOP5 | | | 2024-05- | 17 | MY1 | | 12.52 | | | mg | Each | | | |
| Manufacturing Pro | occess Information | l | | | | | | | | | | | | | | | |
| Terminal Plating / Grid Array Material | | d To | erminal Base Alloy J-ST | | J-STD-020 MSL | MSL Rating | | Peak Process Body Temperat | | mperatur | ture Max Time at Peak T | | Temperature Numb | | Number o | umber of Reflow Cycles | |
| Precious metal (e.g. Ag,Au, NiPdAu) (no Sn) | | i) (no C | CU Alloy 1 | | 1 | | 260 | | | С | | 30 | | seconds 3 | | | |
| Comments | | | | | | | · | | | | | | | | | | |
| evel 1 - maximum time | at peak temperature d | uring sol | dering is 10-3 | 0 seconds | | | | | | | | | | | | | |
| For more information re | egarding material com | position j | please refer to | page 3 | | | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed |
|--|--|--|---|---|---|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | | nium (Cr6+), Polybro | ominated Biphenyls (PBB), Polybron | dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth | |
| cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the | henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies | RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform | ce of its products with European Union membe | ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of |
| RoHS Declaration * 1 - Item(s) | does not contain RoHS restricted substa | ances per the definitio | on above | Supplier Acceptance | * Accepted |
| Exemption: If the declared item does not con applicable exemptions. | ntain RoHS restricted substances per | the definition above | except for defined RoHS exempti | ons, then select the corresponding response i | n the RoHS Declaration above and choose all |
| Exemption List Version | EL-2011/534/EU | | | | |
| Declaration Signature | | | | | |
| Instructions: Complete all of the required fin Requester) and click on Submit Form to have | elds on all pages of this form. Select the form returned to the Requester | he "Accepted" on th | e Supplier Acceptance drop-down | . This will display the signature area. Digital | lly sign the declaration (if required by the |
| Supplier Digital Signature Ra | stislav Drska | Le | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|----------------------------|------------------|--------|--------|-----------------|
| Die | 0.3 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 0.3 | mg |
| Die Attach Epoxy | 0.1 | mg | Supplier | Poly(oxypropylene)diamine | 9046-10-0 | | 0.003 | mg |
| | | | Supplier | Silver (Ag) | 7440-22-4 | | 0.085 | mg |
| | | | Supplier | Proprietary | Proprietary Data | | 0.005 | mg |
| | | | Supplier | Phenolic Resin (Novolac) | 9003-35-4 | | 0.007 | mg |
| Lead Frame | 6.43 | mg | Supplier | Zinc (Zn) | 7440-66-6 | | 0.0077 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 0.1511 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 6.2692 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.0019 | mg |
| Mold Compound-Black | 5.6 | mg | | Epoxy resin | proprietary data | | 0.28 | mg |
| | | | Supplier | Phenolic Resin | Proprietary Data | | 0.112 | mg |
| | | | Supplier | Ortho Cresol Novolac Resin | 29690-82-2 | | 0.14 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | | 0.028 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 5.04 | mg |
| Plating | 0.07 | mg | Supplier | Palladium (Pd) | 7440-05-3 | | 0.0017 | mg |
| | | | В | Nickel (Ni) | 7440-02-0 | | 0.0616 | mg |
| | | | Supplier | Gold (Au) | 7440-57-5 | | 0.0067 | mg |
| Vire Bond - Cu | 0.02 | mg | Supplier | Palladium (Pd) | 7440-05-3 | | 0.0004 | mg |
| | | | Supplier | Gold (Au) | 7440-57-5 | | 0 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 0.0196 | mg |